

General Description

The WSF40N10A is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF40N10A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

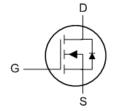
BVDSS	RDSON	ID
100V	42mΩ	31A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

TO-252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter Rating		Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	31	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	22	Α
I _{DM}	Pulsed Drain Current ²	55	А
P _D @T _C =25°C	Total Power Dissipation⁴	52.1	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$
T_J	Operating Junction Temperature Range -55 to 150		

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹		62	°C/W
Rejc	Thermal Resistance Junction-Case ¹		2.4	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.098		V/℃
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =12A		42	55	m()
R _{DS(ON)}		V_{GS} =5.0V , I_D =8A		58	85	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\/ =\/ =250\	0.9	1.5	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.52		mV/℃
	Drain Source Lookage Current	V_{DS} =80V , V_{GS} =0V , T_J =25 $^{\circ}$ C			10	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_J =55 $^{\circ}$ C			100	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =12A		14		S
Qg	Total Gate Charge (10V)			13.5	22	
Q_{gs}	Gate-Source Charge	V_{DS} =80V , V_{GS} =10V , I_{D} =12A		3		nC
Q_{gd}	Gate-Drain Charge			9		
T _{d(on)}	Turn-On Delay Time			6.5		
Tr	Rise Time	V_{DD} =50V , V_{GS} =10V ,		18		no
$T_{d(off)}$	Turn-Off Delay Time	R_G =3.3 Ω I_D =12A		20		ns
T _f	Fall Time			5		
C _{iss}	Input Capacitance			840	1340	
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		115		pF
C _{rss}	Reverse Transfer Capacitance			80		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			12	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.3	V
t _{rr}	Reverse Recovery Time	 IF=12A_dI/dt=100A/µs,Tյ=25℃		40		nS
Q _{rr}	Reverse Recovery Charge	- 127,απαι-1007/μ3,13-23 €		70		nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- 4. Guaranteed by design, not subject to production



Typical Characteristics

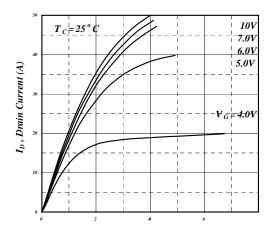


Fig 1. Typical Output Characteristics

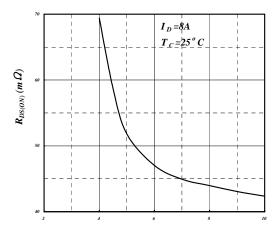


Fig 3. On-Resistance v.s. Gate Voltage

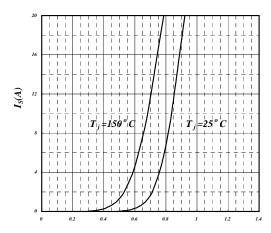


Fig 5. Forward Characteristic of Reverse Diode

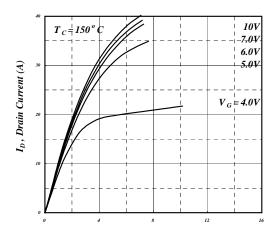


Fig 2. Typical Output Characteristics

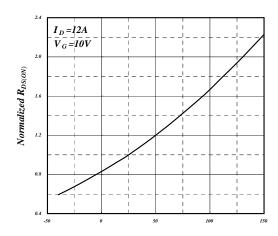


Fig 4. Normalized On-Resistance v.s. Junction Temperature

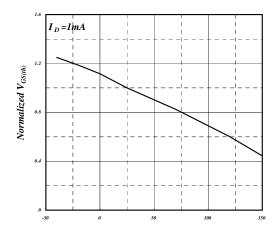


Fig 6. Gate Threshold Voltage v.s.
Junction Temperature



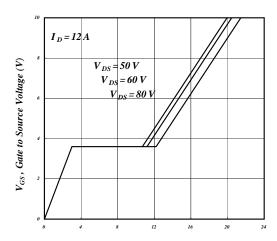


Fig 7. Gate Charge Characteristics

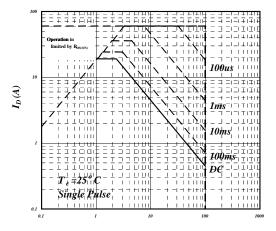


Fig 9. Maximum Safe Operating Area

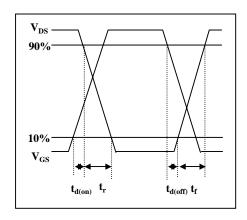


Fig 11. Switching Time Waveform

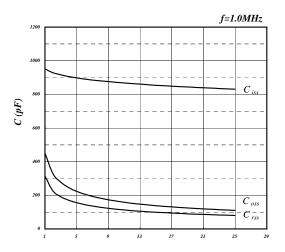


Fig 8. Typical Capacitance Characteristics

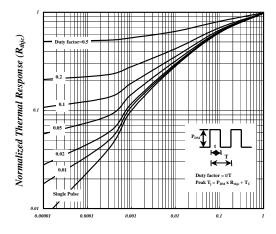


Fig 10. Effective Transient Thermal Impedance

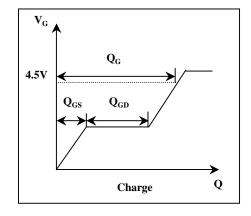
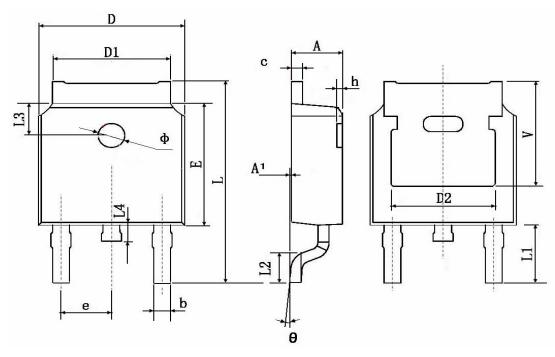


Fig 12. Gate Charge Waveform



TO-252 Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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